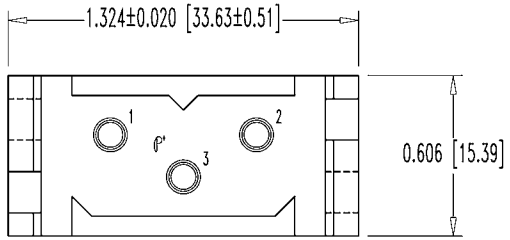
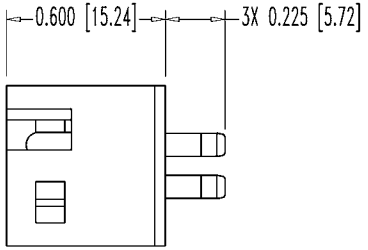
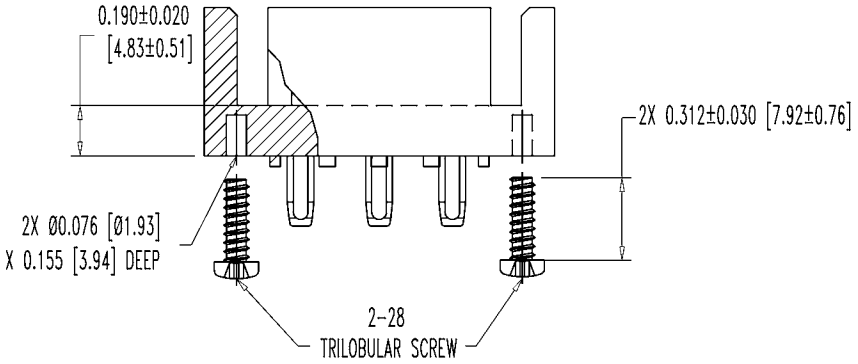
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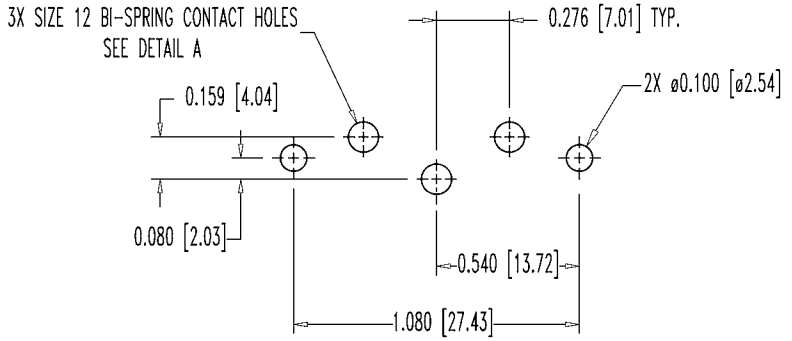
SK6142

DATE	REV	REVISION RECORD	APP	DR	CK
4-14 05	NC	ECO 23955	RCW	YK	TK
9-12 05	A	ECO 24585		LO	



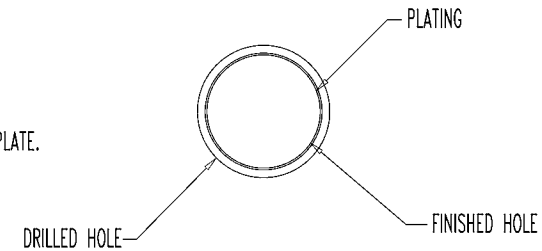






CONTACT HOLE PATTERN

NOTES:
1. MATERIALS AND FINISHES:
   INSULATOR: GLASS FILLED POLYESTER, UL 94V-0, COLOR BLUE.
   CONTACTS: PRECISION MACHINED COPPER ALLOY WITH GOLD FLASH OVER NICKEL PLATE.
   MOUNTING SCREWS: STEEL, ZINC PLATE.
2. ELECTRICAL CHARACTERISTICS:
   CONTACT CURRENT RATING: 40 AMPERES CONTINUOUS PER IEC 512-3, TEST 5b
   INITIAL CONTACT RESISTANCE: 0.001 OHMS MAXIMUM PER IEC 512-2, TEST 2b.
   INSULATOR RESISTANCE: 5 G. OHMS PER IEC 512-2 TEST 3a.
   WORKING VOLTAGE: 1,250 V. r.m.s.
3. TEMPERATURE RANGE: -55°C TO 125°C.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].



PRESS-FIT CONTACT HOLE SEE SK6370

DETAIL A

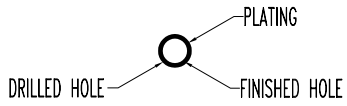
POSITRONIC INDUSTRIES INC.
www.connectpositronic.com

DECIMAL TOL. ± 0.015 [0.38]	PCS SERIES	SCALE N.T.S.	DRAWN BY YK
			APPROVED BY R. WILLIAMS
ANGULAR TOL. ±5°	TITLE PLB3W3M93ST30A1		
	DATE 4-14-05	DRAWING NUMBER SK6142	REV. A

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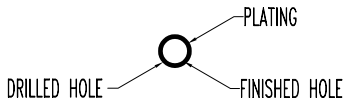
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DATE	REV	REVISION RECORD	APP	DR	CK
8-5 05	NC	ECO 24469	RCW	TK	TK
2-28 06	A	ECO 25575	RCW	YK	TK
5-10 06	B	ECO 25921	TK	ME	TK
8-14 06	C	ECO 26510		YK	



SIZE 20 AND 22 OMEGA CONTACT HOLE

SIZE 20-22 OMEGA CONTACT HOLE			
BOARD TYPE	DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	Ø1.150±0.025 [Ø0.0453±0.0010]	15µ[0.0006] MINIMUM SOLDER OVER 25µ[0.0010] MIN. COPPER	Ø1.000+0.090-0.060 [Ø0.0394+0.0035-0.0024]
COPPER PCB	Ø1.19±0.05 [Ø0.047±0.002]	25µ[0.0010] MIN. COPPER	Ø1.09±0.05 [Ø0.043±0.002]
IMMERSION TIN PCB	Ø1.19±0.05 [Ø0.047±0.002]	0.85±0.15µ [0.000033±0.000006] IMMERSION TIN OVER 25µ[0.0010] MIN. COPPER	Ø1.09±0.05 [Ø0.043±0.002]
IMMERSION SILVER PCB	Ø1.19±0.05 [Ø0.047±0.002]	0.34±0.17µ [0.000013±0.000007] IMMERSION SILVER OVER 25µ[0.0010] MIN. COPPER	Ø1.09±0.05 [Ø0.043±0.002]
ELECTROLESS NICKEL/IMMERSION GOLD PCB	Ø1.19±0.05 [Ø0.047±0.002]	0.05µ[0.000002] MIN. IMMERSION GOLD OVER 4.5±1.5µ [0.000177±0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25µ[0.0010] MIN. COPPER	Ø1.09±0.05 [Ø0.043±0.002]



SIZE 20 BI-SPRING CONTACT HOLE

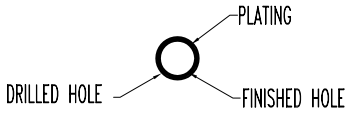
SIZE 20 BI-SPRING CONTACT HOLE			
BOARD TYPE	DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB		3µ [0.0001] MINIMUM SOLDER OVER 25µ[0.0010] MIN. COPPER	Ø1.19±0.05 [Ø0.047±0.002]

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DECIMAL TOL. ±0.38[0.015]	COMPLIANT TERMINATION CONTACTS	SCALE N.T.S.	DRAWN BY TKEPLEY
			APPROVED BY RCW
	TITLE PLATED PCB HOLES		
ANGULAR TOL. ±5°	DATE 8-5-05	DRAWING NUMBER SK6370 SHEET 1 OF 2	REV. C

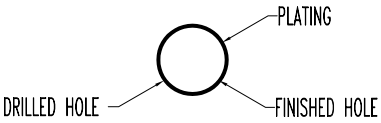
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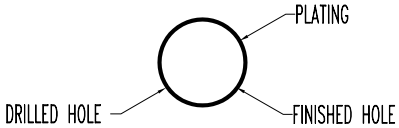
SIZE 16 BI-SPRING CONTACT HOLE

SIZE 16 PRESS=FIT CONTACT HOLE			
BOARD TYPE	DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	Ø1.750±0.025 [Ø0.0689±0.0010]	15µ[0.0006] MINIMUM SOLDER OVER 25µ[0.0010] MIN. COPPER	Ø1.600+0.090-0.060 [Ø0.0630+0.0035-0.0024]
COPPER PCB	Ø1.73±0.05 [Ø0.068±0.002]	25µ[0.0010] MIN. COPPER	Ø1.600+0.090-0.060 [Ø0.0630+0.0035-0.0024]
IMMERSION TIN PCB	Ø1.73±0.05 [Ø0.068±0.002]	0.85±0.15µ [0.000033±0.000006] IMMERSION TIN OVER 25µ[0.0010] MIN. COPPER	Ø1.600+0.090-0.060 [Ø0.0630+0.0035-0.0024]
IMMERSION SILVER PCB	Ø1.73±0.05 [Ø0.068±0.002]	0.34±0.17µ [0.000013±0.000007] IMMERSION SILVER OVER 25µ[0.0010] MIN. COPPER	Ø1.600+0.090-0.060 [Ø0.0630+0.0035-0.0024]
ELECTROLESS NICKEL PCB	Ø1.73±0.05 [Ø0.068±0.002]	0.05µ[0.000002] MIN. IMMERSION GOLD OVER 4.5±1.5µ [0.000177±0.000059] ELECTROLESS NICKEL PER IPC-4552 OVER 25µ[0.0010] MIN. COPPER	Ø1.600+0.090-0.060 [Ø0.0630+0.0035-0.0024]



SIZE 12 BI-SPRING CONTACT HOLE

SIZE 12 BI-SPRING CONTACT HOLE			
BOARD TYPE	DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	Ø2.54±0.03 [Ø0.100±0.001]	15µ[0.0006] MINIMUM SOLDER OVER 25µ[0.0010] MIN. COPPER	Ø2.39±0.05 [Ø0.094±0.002]



SIZE 8 BI-SPRING CONTACT HOLE

SIZE 8 BI-SPRING CONTACT HOLE			
BOARD TYPE	DRILLED HOLE SIZE	RECOMMENDED PLATING	FINISHED HOLE SIZES
TIN-LEAD SOLDER PCB	Ø3.18±0.03 [Ø0.125±0.001]	15µ[0.0006] MINIMUM SOLDER OVER 25µ[0.0010] MIN. COPPER	Ø3.02±0.05 [Ø0.119±0.002]

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